

MIL-C-14550B
Amendment 3
20 March 1987
Superseding
Amendment 2
20 November 1985

Military Specification

Copper Plating (Electrodeposited)

This amendment forms a part of MIL-C-14550B dated 2 December 1983, and is approved for use by all Departments and Agencies of the Department of Defense.

Page 2

2.2 Other publications. Add the following:

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| "B504 | Method for Measurement of Thickness of Metallic Coatings by the Coulometric Method |
| P567 | Method for Measurement of Coating Thickness by the Beta Backscatter Method |
| P568 | Method for Measurement of Coating Thickness by X-Ray Spectrometry" |

Page 3

3.7 Hydrogen embrittlement relief. Delete paragraph and replace with the following:

"All steel parts having a hardness of Rockwell C35 and higher shall be baked at $191^{\circ} \pm 14^{\circ}\text{C}$ ($375^{\circ} \pm 25^{\circ}\text{F}$) for twenty-four hours, within four hours after plating to provide hydrogen embrittlement relief. Plated springs and other parts subject to flexure shall not be flexed prior to the baking operations."

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4.5.1 Thickness. Delete paragraph and replace with the following:

"Unless otherwise specified, a destructive thickness measurement shall be determined in accordance with the microscopic test method ASTM P487. Other applicable tests may be performed at the option of the supplier. These tests include the destructive coulometric test ASTM P504 and other applicable nondestructive tests; ASTM P499 (magnetic) ASTM P567 (beta radiation backscatter) or ASTM P568 (X-ray spectrometry)."

AMSC N/A

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Custodians

Army - MR

Navy - AS

Air Force - 20

Preparing Activity

Army - MP

Project No. MFFP-0390

Review Interest

Army - MI

Navy - AS, SH, EC

User Interest

Army - MI

Navy - SH

/APFA-MFFP/